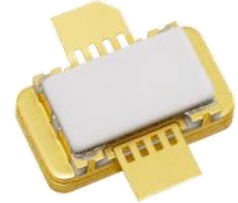


■ Features

- High Voltage Operation : $V_{DS}=50V$
- High Power : 52.5dBm (typ.) @ P_{sat}
- Proven Reliability

■ Description

Sumitomo Electric's GaN-HEMT offers high efficiency, ease of matching, greater consistency and broad bandwidth for high power L-band amplifiers with 50V operation, and gives you higher gain. This new product is ideally suited for use from 2.3GHz to 2.7GHz W-CDMA and LTE design requirements as it offers high gain, long term reliability and ease of use.


ABSOLUTE MAXIMUM RATINGS (Case Temperature $T_c=25\text{deg.C}$)

Item	Symbol	Condition	Rating	Unit
Operating Voltage	V_{DS}		55	V
Drain-Source Voltage	V_{DS}	$V_{GS}=-8V$	160	V
Gate-Source Voltage	V_{GS}		-15	V
Total Power Dissipation	P_t		140.6	W
Storage Temperature	T_{stg}		-65 to +175	deg.C
Channel Temperature	T_{ch}		250	deg.C

RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
DC Input Voltage	V_{DS}		≤ 55	V
Forward Gate Current	I_{GF}	$R_G=5\text{ ohm}$	≤ 142	mA
Reverse Gate Current	I_{GR}	$R_G=5\text{ ohm}$	≥ -5.2	mA
Channel Temperature	T_{ch}		≤ 200	deg.C
Average Output Power	$P_{ave.}$		≤ 49.5	dBm

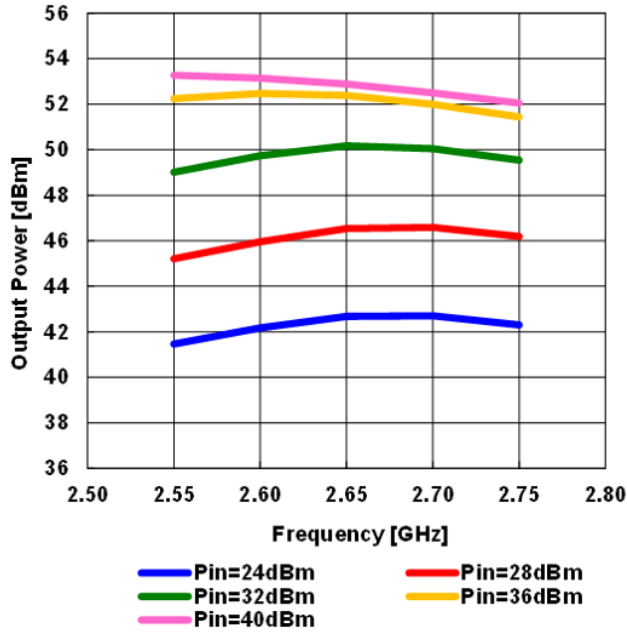
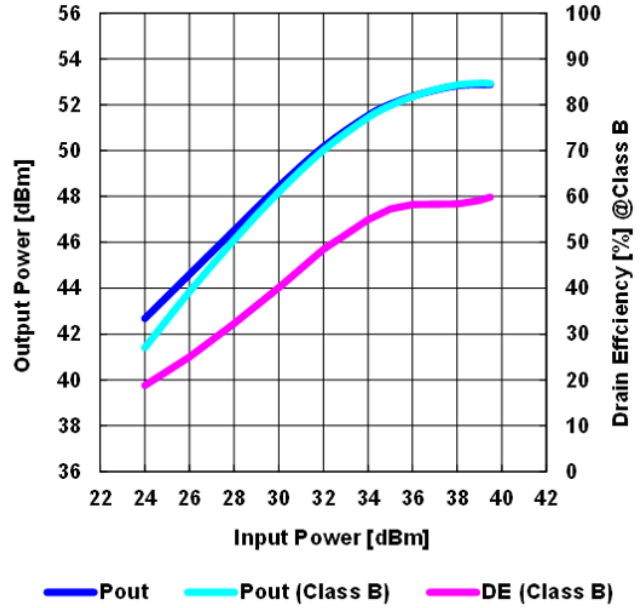
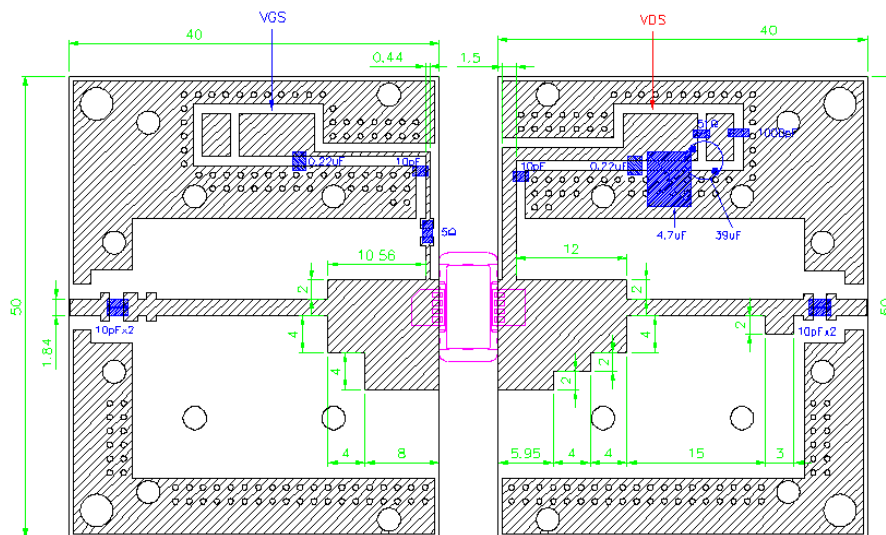
ELECTRICAL CHARACTERISTICS (Case Temperature $T_c=25\text{deg.C}$)

Item	Symbol	Condition	Limit			Unit
			Min.	Typ.	Max.	
Pinch-Off Voltage	V_p	$V_{DS}=50V$ $I_{DS}=36mA$	-4.0	-	-2.0	V
Saturated Power	$P_{sat} *1$	$V_{DS}=50V$	51.5	52.5	-	dBm
Drain Efficiency at P_{sat}	$DE *1$	$I_{DS(DC)}=0mA$ $f=2.65GHz$	53.0	60.0	-	%
Power Gain	$G_p *2$	$V_{DS}=50V$ $I_{DS(DC)}=600mA$ $f=2.65GHz$	15.5	16.5	-	dB
Thermal Resistance	R_{th}	Channel to Case at 78W P_{DC}	-	1.4	1.6	deg.C/W

*1 : 10%-duty RF pulse (DC supply constant), Fixed Pin=39dBm

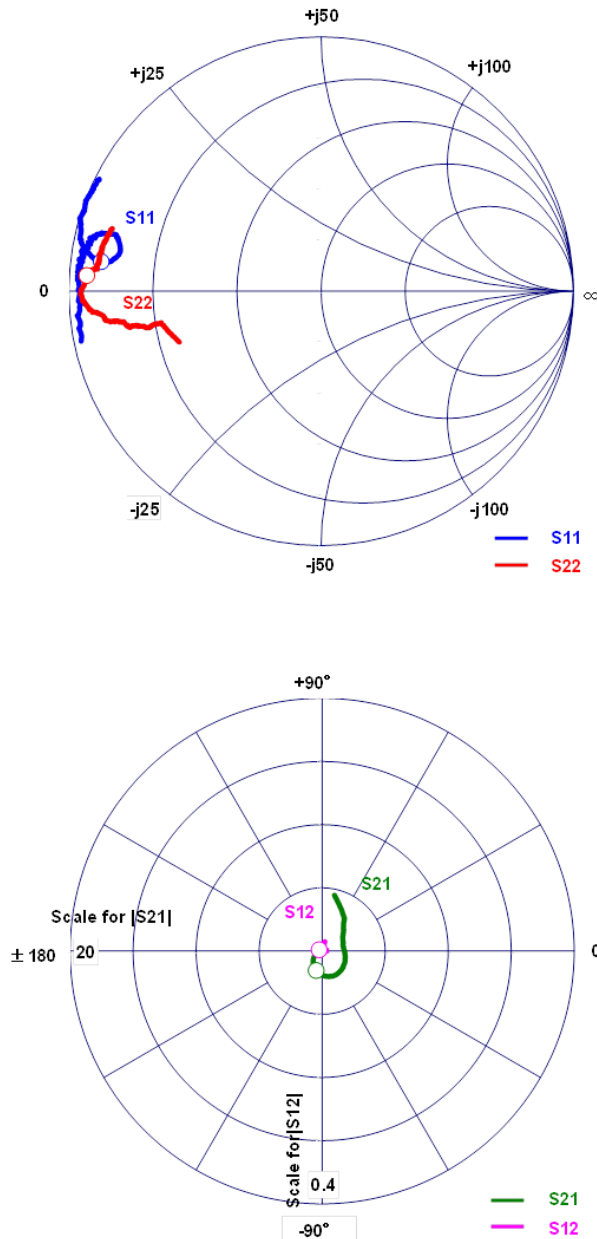
*2 : $P_{out}=44.5dBm$, CW modulation Signal (W-CDMA)

RoHS Compliance	YES
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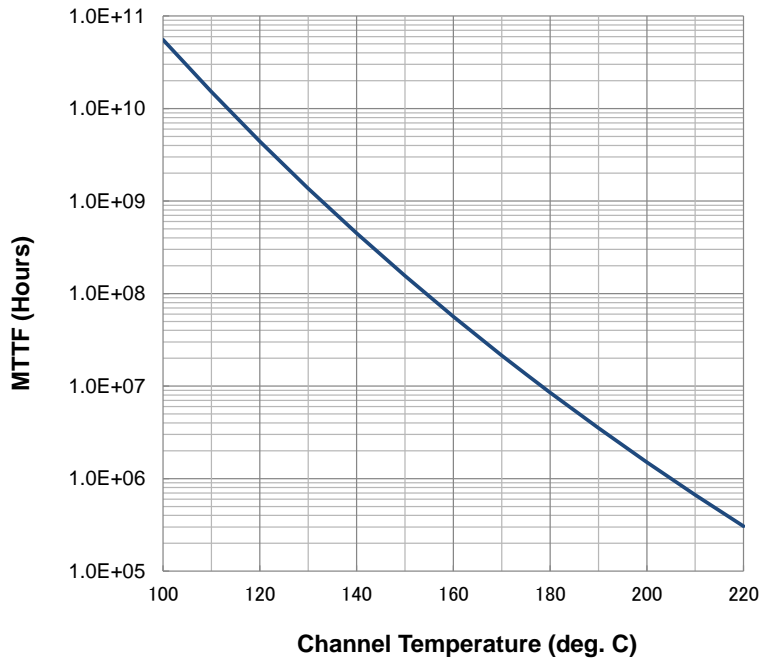
RF characteristics @f=2.65GHz fine tuned
Output Power vs. Frequency
 $V_{DS}=50V$ $I_{DS(DC)}=900mA$

Output Power and Drain Efficiency vs. Input Power
 $V_{DS}=50V$ $I_{DS(DC)}=900mA$ $f=2.65GHz$

Pulse Signal (10%-duty, DC : constant)
Test Fixture

 $h=0.8mm$ $\epsilon_r=3.5$
 $Cu=18\mu m$ Unit: mm

- Reference DATA -

S-Parameters @VDS=50V, IDS(DC)=900mA, f=0.5 to 4.5GHz
ZI = Zs = 50ohm Marker : 2.65GHz



Freq. GHz	S11		S21		S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.5	0.97	-168.33	4.53	77.54	0.005	6.65	0.60	-160.38
0.6	0.96	-175.67	3.72	66.82	0.005	3.61	0.62	-164.49
0.7	0.96	177.21	3.14	55.80	0.005	-1.98	0.65	-168.57
0.8	0.96	176.73	2.75	51.59	0.005	-5.54	0.66	-168.96
0.9	0.96	175.17	2.47	46.84	0.005	-0.58	0.68	-168.60
1.0	0.96	174.45	2.29	41.94	0.005	-4.86	0.70	-168.32
1.1	0.96	173.85	2.09	37.54	0.005	-8.19	0.72	-168.64
1.2	0.96	172.40	1.95	33.05	0.004	-3.86	0.73	-169.20
1.3	0.96	171.88	1.87	28.76	0.004	-5.48	0.75	-169.44
1.4	0.96	171.15	1.83	23.63	0.005	-4.06	0.77	-169.47
1.5	0.96	170.55	1.76	19.11	0.004	-7.45	0.78	-170.15
1.6	0.95	169.37	1.72	14.06	0.005	-5.52	0.79	-171.02
1.7	0.93	167.70	1.72	7.93	0.004	-10.23	0.81	-171.51
1.8	0.93	166.94	1.77	1.99	0.004	-17.41	0.83	-171.61
1.9	0.92	166.27	1.81	-5.39	0.004	-17.44	0.85	-172.07
2.0	0.90	165.69	1.88	-12.23	0.004	-29.05	0.87	-172.67
2.1	0.88	165.25	1.97	-22.78	0.004	-36.75	0.88	-174.08
2.2	0.85	164.71	2.06	-34.99	0.004	-61.66	0.91	-174.74
2.3	0.83	165.88	2.14	-48.52	0.004	-86.89	0.93	-176.69
2.4	0.81	168.49	2.16	-64.97	0.004	-123.00	0.95	-178.83
2.5	0.83	170.91	2.00	-82.72	0.004	-155.78	0.94	179.05
2.6	0.86	172.33	1.75	-99.89	0.005	172.61	0.93	176.88
2.7	0.90	172.17	1.48	-113.74	0.005	150.38	0.93	175.79
2.8	0.92	171.30	1.23	-124.98	0.006	133.81	0.91	174.70
2.9	0.95	170.26	1.02	-134.71	0.006	121.97	0.90	174.55
3.0	0.96	169.09	0.85	-141.85	0.006	113.19	0.89	174.16
3.1	0.98	167.82	0.71	-147.89	0.007	106.63	0.89	173.47
3.2	0.98	166.51	0.62	-154.06	0.007	102.93	0.89	173.01
3.3	0.98	165.46	0.54	-158.56	0.007	97.46	0.89	172.59
3.4	0.99	164.36	0.47	-163.02	0.008	94.08	0.89	172.33
3.5	1.00	163.48	0.42	-166.87	0.008	89.70	0.89	171.43
3.6	0.99	162.25	0.38	-170.13	0.009	88.09	0.89	170.58
3.7	0.99	161.43	0.34	-174.43	0.009	87.00	0.88	170.16
3.8	0.99	160.30	0.32	-177.76	0.009	83.46	0.88	169.37
3.9	1.00	159.24	0.29	-178.56	0.010	83.23	0.88	168.59
4.0	0.99	158.21	0.27	-174.81	0.010	83.32	0.88	167.62
4.1	0.99	157.52	0.26	-171.47	0.011	81.50	0.88	167.05
4.2	0.99	156.49	0.24	-167.38	0.012	80.72	0.88	166.40
4.3	0.99	155.17	0.23	-163.29	0.013	76.60	0.87	165.30
4.4	0.99	154.27	0.22	-159.25	0.014	75.14	0.87	164.43
4.5	0.98	153.35	0.22	-155.30	0.015	73.17	0.86	163.42

**MTTF Calculation
- Estimated MTTF -**


Ea=1.6eV
Confidence Level=90%

Channel Temp (deg.C)	MTTF (Hours)
160	5.98 x 10 ⁷
180	9.02 x 10 ⁶
200	1.60 x 10 ⁶

$$AF = \exp\left[-\frac{Ea}{k}\left(\frac{1}{T_{\text{stress}}} - \frac{1}{T_{\text{use}}}\right)\right]$$

$$MTTF_{\text{use}} = MTTF_{\text{stress}} * AF$$

Where;

AF: acceleration factor

Ea: activation energy (1.6 eV)

k: Boltzman's constant (8.62 x 10⁻⁵ eV/K)

T_{stress}: stress temperature (K)

T_{use}: use temperature (K)

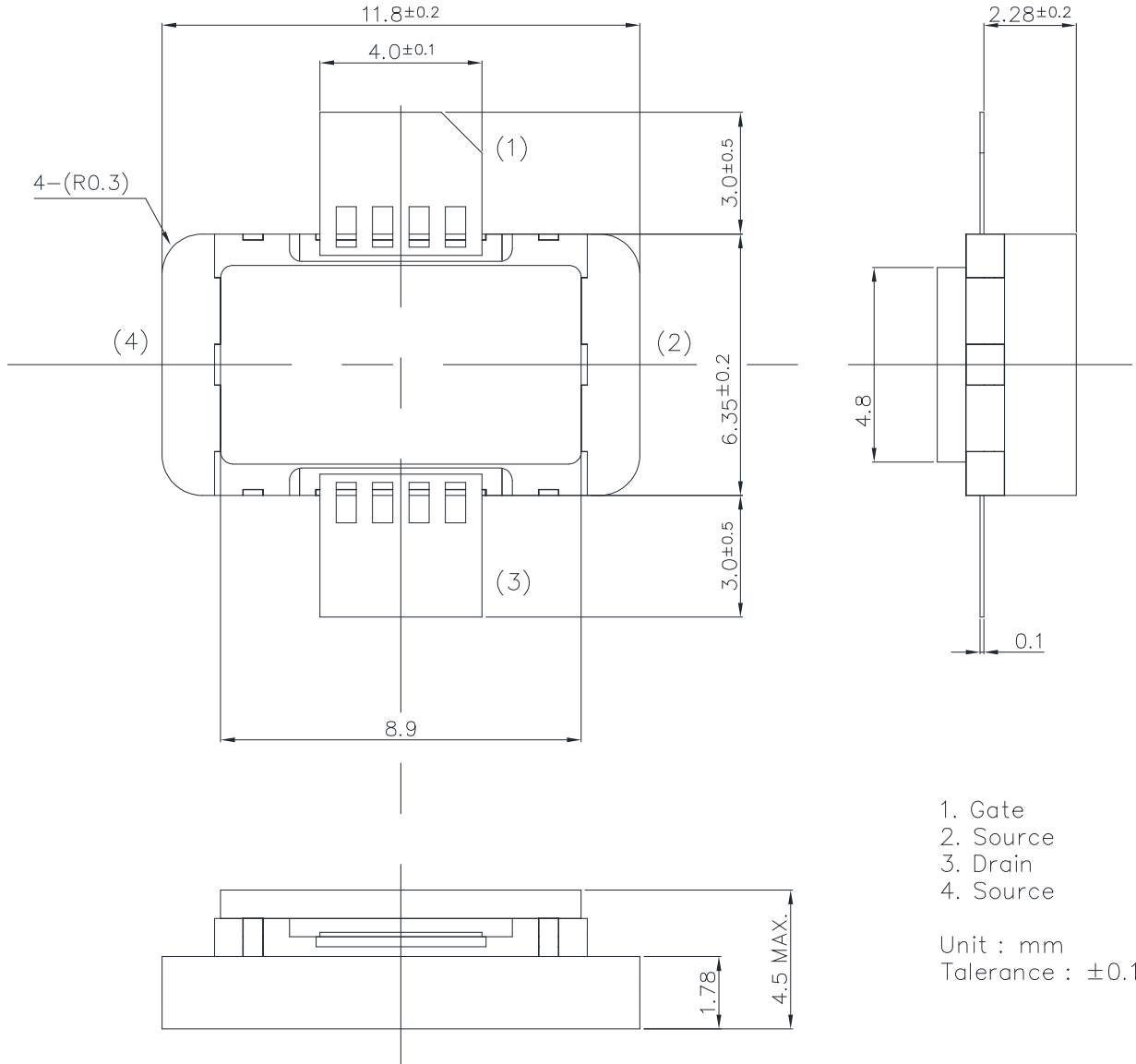
ESD characteristic

Test Methodology	Class
Human Body Model (per JESD22-A114)	1C
Machine Model (per JEIA/ESD22-A115)	B
Device Charged Model (per JESD22-C101)	IV

Ordering Information

Part Number	MOQ / MOU	Tray Style
SGN26H180M1H	No Limitation	30pcs Tray (30 pockets)
SGN26H180M1H/001	No Limitation	JEDEC Tray (100 pockets)

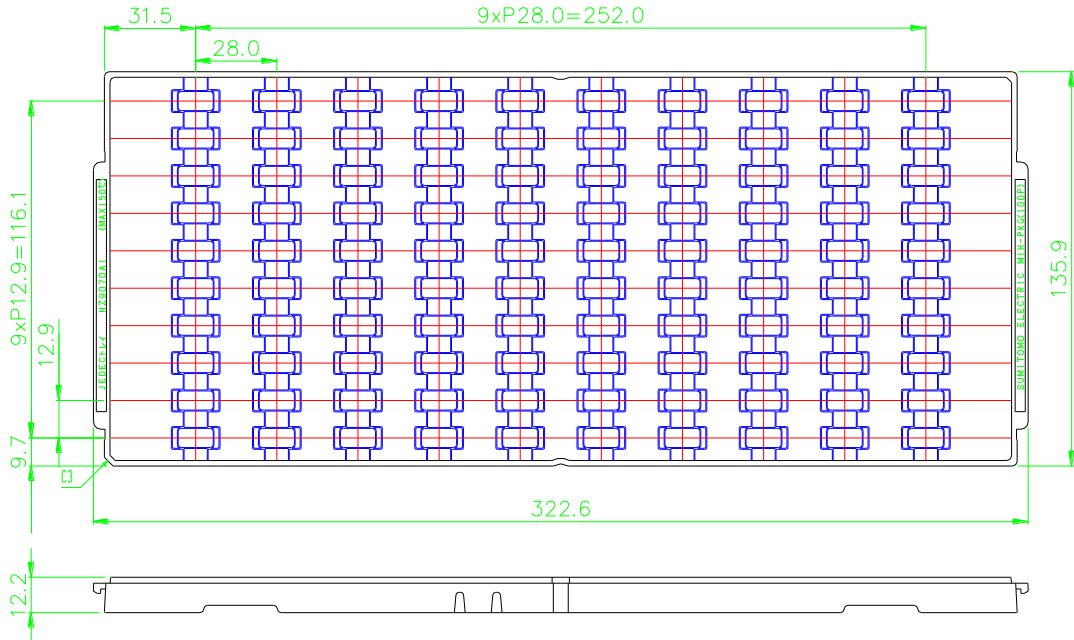
M1H Package Outline
Metal-Ceramic Hermetic Package



1. Gate
2. Source
3. Drain
4. Source

Unit : mm
Tolerance : ± 0.15

TRAY SIZE : M1H



For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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